

Amendments to the Specification

Please amend the title beginning on page 1, line 2 as follows:

~~Semiconductor Device and Method for Manufacturing Semiconductor Device Having Heat Conducting Plates~~

Please amend the paragraph beginning at page 1, line 5 as follows:

This application is a continuation application of U.S. Patent Application Serial No. 10/127,613, which is based on and incorporates herein by reference Japanese Patent Application No. 2000-127516, which was filed on April 25, 2001.

Please amend the paragraph beginning at page 7, line 1 as follows:

As shown in Fig. 1, the mold resin 19, which is made of a material such as epoxy resin, fills the space between the insulating sheets 13, 14 18 to surround the chip 12 and the heat sink coupler 15. A mold 20 is used to mold the resin 19 to a stack that includes the semiconductor chip 12, the heat sink coupler 15, the heat sinks 13, 14, and the insulating sheets 18. The mold 20 has a simple structure of a lower mold 21 and an upper mold 22, so the production cost of the semiconductor device 11 is relatively low. When the stack 8 is held in a cavity 23 of the mold 20, the insulating sheets 18 are pressed between the mold 20 and the heat sinks 13, 14 and compressively deformed by about 10 to 40%. Therefore, when the molten mold resin 19 is injected into the cavity 23, the resin 19 is prevented from covering the insulating sheets 18 on the surface pressed by the mold 20. In addition, the force applied to the chip 12 while the stack is pressed by the mold 20 is damped and distributed by the sheets 18, so the chip 12 is not broken.